

A technique for electrically interconnecting a signal between a first circuit board and a second circuit board is disclosed. In each board, at least one signal conductor is shielded by an electrically conductive shield. Multiple conductors may be shielded by the same shield. A first opening is formed in the electrically conductive shield of the first circuit board and a second opening is formed in the electrically conductive shield of the second circuit board so as to expose the signal conductor in the each circuit board. An electrically conductive adhesive, reflowed solder paste, or interposer/elastomer device is applied surrounding at least one of the openings and may further be applied within at least one of the openings. The first circuit board and the second circuit board are then positioned such that the first opening and the second opening are aligned and a signal propagating along the first signal conductor is electrically interconnected to the second signal conductor.